



Semiconductor Device Type: SL / F / TF (D7X) 016 SOIC .150in Matte Tin				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			JEDEC 97 Product Marking and/or Pkg. Labeling e3
Basic Substance	CAS Number	Contained in Sub-Component	% Total Weight	mg/part	ppm	60.00	(mg) Total	Mold Compound	% of Total Weight	38.12
Silica, vitreous	60676-86-0	Mold Compound	32.402	51.001	324,020		Silica, vitreous	60676-86-0	85.00	
Epoxy Resin (No bromine, No diantimony trioxide)	Trade Secret	Mold Compound	2.335	3.675	23,349		Epoxy Resin	Trade Secret	6.13	
Phenolic Resin (No Br / CL SbO3, No diantimony trioxide)	Trade Secret	Mold Compound	2.335	3.675	23,349		Phenolic Resin	Trade Secret	6.13	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	0.934	1.470	9,339		Epoxy, Cresol Novolac	29690-82-2	2.45	
Carbon Black	1333-86-4	Mold Compound	0.114	0.180	1,144		Carbon Black	1333-86-4	0.30	
							Total			100.00
Copper	7440-50-8	Lead Frame	24.276	38.211	242,761	40.00	(mg) Total	Lead Frame	% of Total Weight	25.41
Iron	7439-89-6	Lead Frame	0.597	0.940	5,971		Copper	7440-50-8	95.54	
Silver	7440-22-4	Lead Frame	0.484	0.762	4,841		Iron	7439-89-6	2.35	
Zinc	7440-66-6	Lead Frame	0.032	0.050	318		Silver	7440-22-4	1.91	
Phosphorous	7723-14-0	Lead Frame	0.021	0.033	210		Zinc	7440-66-6	0.13	
Silver	7440-22-4	Die Attach	2.618	4.120	26,175		Phosphorous	7723-14-0	0.08	
Diester Resin	94-80-4	Die Attach	0.524	0.824	5,235		Total			100.00
Functionalized Urethane Resin	72869-86-4	Die Attach	0.175	0.275	1,745	5.49	(mg) Total	Die Attach	% of Total Weight	3.49
Epoxy Resin	9003-36-5	Die Attach	0.087	0.137	873		Silver	7440-22-4	75.00	
Epoxy Resin	13561-08-5	Die Attach	0.087	0.137	873		Diester Resin	94-80-4	15.00	
Silicon	7440-21-3	Chip (Die)	3.180	5.005	31,800		Functionalized Urethane Resin	72869-86-4	5.00	
Gold	7440-57-5	Wire Bond	1.210	1.905	12,100		Epoxy Resin	9003-36-5	2.50	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	28.590	45.001	285,900		Epoxy Resin	13561-08-5	2.50	
TOTALS:						100.000	157.400	1,000.000		
0.1574 g Total Mass										
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)										
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.										
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.										
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/										
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.										
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table										
						60.00	(mg) Total	Chip (Die)	% of Total Weight	3.18
							Doped Silicon	7440-21-3	100.00	
							Total			100.00
						1.90	(mg) Total	Wire Bond	% of Total Weight	1.21
							Doped Gold	7440-57-5	100.00	
							Total			100.00
						45.00	(mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	28.59
							Tin	7440-31-5	100.00	
							Total			100.00
						157.400				100.000